onsemi

Zener Voltage Regulators

500 mW, Low I_Z SOD-523 Surface Mount

MM5Z4xxxTxG Series, SZMM5Z4xxxTxG Series

This series of Zener diodes is packaged in a SOD–523 surface mount package. They are designed to provide voltage regulation protection and are especially attractive in situations where space is at a premium. They are well suited for applications such as cellular phones, hand held portables, and high density PC boards.

Features

- 500 mW Rating on FR-4 or FR-5 Board
- Wide Zener Reverse Voltage Range 1.8 V to 43 V
- Low Reverse Current $(I_{ZT}) 50 \mu A$
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant*

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic case FINISH: Corrosion resistant finish, easily solderable MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES: 260°C for 10 Seconds

POLARITY: Cathode indicated by polarity band **FLAMMABILITY RATING:** UL 94 V–0

MAXIMUM RATINGS

Rating	Symbol	Max	Units
Total Power Dissipation on FR–5 Board, (Note 1) @ T _L = 75°C Derated above 75°C	P _D	500 4.0	mW mW/°C
Thermal Resistance, (Note 2) Junction-to-Ambient	R_{\thetaJA}	250	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

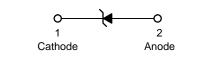
1. $FR-5 = 3.5 \times 1.5$ inches, using the minimum recommended footprint.

2. Thermal Resistance measurement obtained via infrared Scan Method.

*For additional information on our Pb–Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



SOD-523 CASE 502 STYLE 1



MARKING DIAGRAM



XX = Specific Device Code

M = Date Code*

= Pb–Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MM5Z4xxxT1G	SOD–523 (Pb–Free)	3,000 / Tape & Reel
SZMM5Z4xxxT1G	SOD-523 (Pb-Free)	3,000 / Tape & Reel
MM5Z4xxxT5G	SOD-523 (Pb-Free)	8,000 / Tape & Reel
SZMM5Z4xxxT5G	SOD-523 (Pb-Free)	8,000 / Tape & Reel

⁺For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DEVICE MARKING INFORMATION

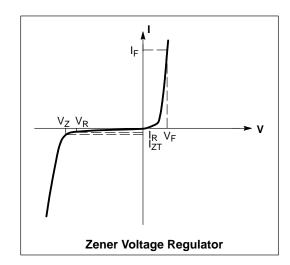
See specific marking information in the device marking column of the Electrical Characteristics table on page 3 of this data sheet.

DATA SHEET

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted, V_F = 0.9 V Max. @ I_F = 10 mA)

Symbol	Parameter		
VZ	Reverse Zener Voltage @ I _{ZT}		
I _{ZT}	Reverse Current		
I _R	Reverse Leakage Current @ V _R		
V _R	Reverse Voltage		
١ _F	Forward Current		
V _F	Forward Voltage @ I _F		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

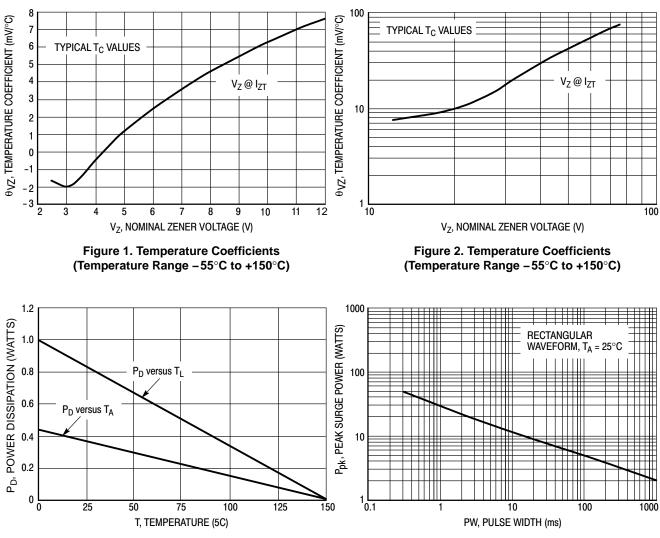


ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted, V_F = 0.9 V Max. @ I_F = 10 mA)

		Zener Voltage (Note 3)				Leakage Current	
	Device		V _Z (Volts)		@ I _{ZT}	zt I _R @ V _R	
Device*	Marking	Min	Nom	Max	μΑ	μΑ	Volts
MM5Z4678T1G/T5G*	4A	1.71	1.8	1.89	50	7.5	1
MM5Z4679T1G/T5G*	42	1.90	2.0	2.10	50	5	1
MM5Z4680T1G/T5G	4C	2.09	2.2	2.31	50	4	1
MM5Z4681T1G/T5G*	4D	2.28	2.4	2.52	50	2	1
MM5Z4682T5G	4E	2.565	2.7	2.835	50	1	1
MM5Z4683T1G/T5G*	4F	2.85	3.0	3.15	50	0.8	1
MM5Z4684T1G/T5G*	4G	3.13	3.3	3.47	50	7.5	1.5
MM5Z4685T1G/T5G	4H	3.42	3.6	3.78	50	7.5	2
MM5Z4686T1G/T5G	43	3.70	3.9	4.10	50	5	2
MM5Z4687T1G/T5G	4J	4.09	4.3	4.52	50	4	2
MM5Z4688T1G/T5G	4K	4.47	4.7	4.94	50	10	3
MM5Z4689T1G/T5G	4L	4.85	5.1	5.36	50	10	3
MM5Z4690T1G/T5G	4M	5.32	5.6	5.88	50	10	4
MM5Z4691T1G/T5G*	4N	5.89	6.2	6.51	50	10	5
MM5Z4692T1G/T5G*	44	6.46	6.8	7.14	50	10	5.1
MM5Z4693T1G/T5G	4P	7.13	7.5	7.88	50	10	5.7
MM5Z4694T5G	4Q	7.79	8.2	8.61	50	1	6.2
MM5Z4695T1G/T5G*	4R	8.27	8.7	9.14	50	1	6.6
MM5Z4696T1G/T5G*	45	8.65	9.1	9.56	50	1	6.9
MM5Z4697T1G/T5G	4T	9.50	10	10.50	50	1	7.6
MM5Z4698T1G/T5G*	4U	10.45	11	11.55	50	0.05	8.4
MM5Z4699T5G	4V	11.40	12	12.60	50	0.05	9.1
MM5Z4700T1G/T5G*	4W	12.35	13	13.65	50	0.05	9.8
MM5Z4701T1G/T5G*	4X	13.30	14	14.70	50	0.05	10.6
MM5Z4702T5G	4Y	14.25	15	15.75	50	0.05	11.4
MM5Z4703T1G/T5G*	4Z	15.20	16	16.80	50	0.05	12.1
MM5Z4704T1G/T5G*	46	16.15	17	17.85	50	0.05	12.9
MM5Z4705T1G/T5G	47	17.10	18	18.90	50	0.05	13.6
MM5Z4706T1G/T5G*	5A	18.05	19	19.95	50	0.05	14.4
MM5Z4707T1G/T5G*	5C	19.00	20	21.00	50	0.01	15.2
MM5Z4708T1G/T5G*	5F	20.90	22	23.10	50	0.01	16.7
MM5Z4709T1G/T5G	5G	22.80	24	25.20	50	0.01	18.2
MM5Z4710T1G/T5G*	5H	23.75	25	26.25	50	0.01	19.0
MM5Z4711T1G/T5G	5K	25.65	27	28.35	50	0.01	20.4
MM5Z4712T1G/T5G*	5L	26.60	28	29.40	50	0.01	21.2
MM5Z4713T1G/T5G*	5N	28.50	30	31.50	50	0.01	22.8
MM5Z4714T1G/T5G	5P	31.35	33	34.65	50	0.01	25.0
MM5Z4715T1G/T5G	5Q	34.20	36	37.80	50	0.01	27.3
MM5Z4716T1G/T5G*	5R	37.05	39	40.95	50	0.01	29.6
MM5Z4717T1G/T5G	5T	40.85	43	45.15	50	0.01	32.6

3. Nominal Zener voltage is measured with the device junction in thermal equilibrium at $T_L = 30^{\circ}C \pm 1^{\circ}C$.

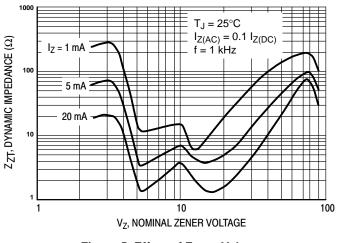
*Please Contact Sales.

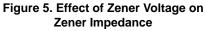


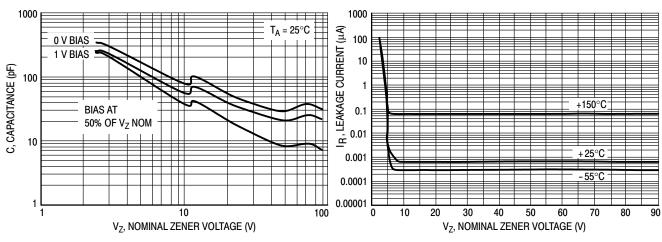
TYPICAL CHARACTERISTICS

Figure 3. Steady State Power Derating

Figure 4. Maximum Nonrepetitive Surge Power



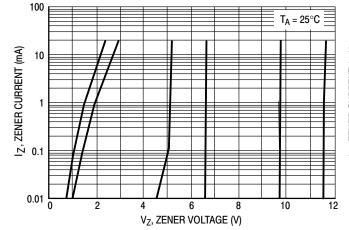


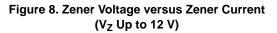


TYPICAL CHARACTERISTICS

Figure 6. Typical Capacitance







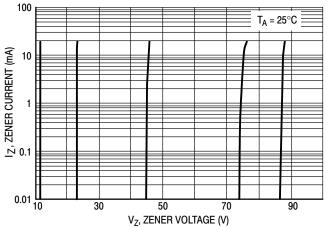
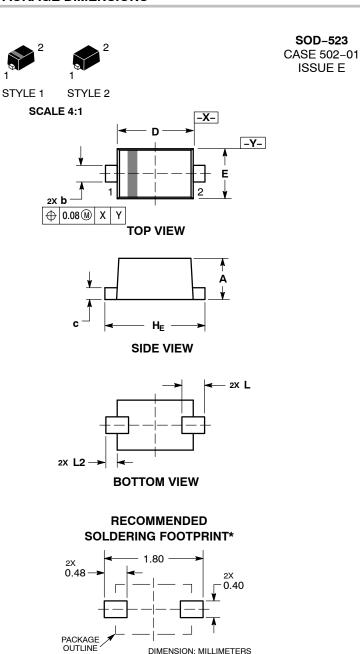


Figure 9. Zener Voltage versus Zener Current (12 V to 91 V)

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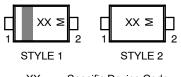
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DIMENSION: MILLIMETERS

- NOTES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- BASE MALERIAL DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PRO-TRUSIONS, OR GATE BURRS. 4.

	MILLIMETERS			
DIM	MIN NOM MAX			
Α	0.50	0.60	0.70	
b	0.25	0.30	0.35	
С	0.07	0.14	0.20	
D	1.10	1.20	1.30	
Е	0.70	0.80	0.90	
ΗE	1.50	1.60	1.70	
L	0.30 REF			
L2	0.15	0.20	0.25	

GENERIC **MARKING DIAGRAM***



XX = Specific Device Code Μ Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " .", may or may not be present.

STYLE 2: NO POLARITY STYLE 1: PIN 1. CATHODE (POLARITY BAND) 2. ANODE

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